

# Ultraform® W 2320 003 LEV AT

## Polyoxymethylene (POM)



### Product Description

Ultraform W 2320 003 LEV AT is a very easy flowing and rapidly solidifying injection molding POM grade for use where processing is extremely difficult but mechanical properties are lower. this grade is designed to achieve low emission and smell.

### Applications

Typical applications include difficult, thin walled parts.

PHYSICAL	ISO Test Method	Property Value
Density, g/cm <sup>3</sup>	1183	1.41
Mold Shrinkage, parallel, %	294-4	2
Mold Shrinkage, normal, %	294-4	2.1
Moisture, %	62	
(50% RH)		0.2
(Saturation)		0.8
RHEOLOGICAL	ISO Test Method	Property Value
Melt Volume Rate (190 C/2.16 Kg), cc/10min.	1133	25
MECHANICAL	ISO Test Method	Property Value
Tensile Modulus, MPa	527	
23C		2,850
Tensile stress at yield, MPa	527	
23C		65
Tensile strain at yield, %	527	
23C		8
Nominal strain at break, %	527	
23C		24
Tensile Creep Modulus (1000h), MPa	899	1,350
IMPACT	ISO Test Method	Property Value
Charpy Notched, kJ/m <sup>2</sup>	179	
-30C		4
23C		4.5
Charpy Unnotched, kJ/m <sup>2</sup>	179	
-30C		190
23C		190
THERMAL	ISO Test Method	Property Value
Melting Point, C	3146	166
HDT A, C	75	100
Coef. of Linear Thermal Expansion, Parallel, mm/mm C		1.1 X10-4
ELECTRICAL	ISO Test Method	Property Value
Comparative Tracking Index	IEC 60112	600
Volume Resistivity (Ohm-m)	IEC 60093	1E11
Surface Resistivity (Ohm)	IEC 60093	1E13

Dielectric Constant (1 MHz)	IEC 60250	3.8
Dissipation Factor (1 MHz), E-4	IEC 60250	50

**Processing Guidelines****Material Handling**

Max. Water content: 0.15%

Product is supplied in polyethylene bags and drying prior to molding is not required. However, after relatively long storage or when handling material from previously opened containers, preliminary drying is recommended in order to remove any moisture which has been absorbed. If drying is required, a dehumidifying or desiccant dryer operating at 80 - 110C (176 - 230F) is recommended. Drying time is dependent on moisture level, however 2-4 hours is generally sufficient. Further information concerning safe handling procedures can be obtained from the Safety Data Sheet. Alternatively, please contact your BASF representative.

**Typical Profile**

Melt Temperature 190-220C (375-428F)

Mold Temperature 60-120C (140-248F)

Injection and Packing Pressure 35-70 bar (500-1000psi)

**Mold Temperatures**

A mold temperature of 60-120C (140-248F) is recommended, however temperatures of as low as 45C (113F) can be used where applicable.

**Pressures**

Injection speed must be optimized. A filling rate which is too high results in anisotropic mechanical properties, while a filling rate which is too low yields parts with poor surface finish. The tool must be vented to avoid burn marks and prevent mold deposits. Injection pressure controls the filling of the part and should be applied for 90% of ram travel. Packing pressure affects the final part and can be used effectively in controlling sink marks and shrinkage. It should be applied and maintained until the gate area is completely frozen off.

Back pressure can be utilized to provide uniform melt consistency and reduce trapped air and gas.

**Fill Rate**

Injection speed must be optimized. A filling rate which is too high results in anisotropic mechanical properties, while a filling rate which is too low yields parts with poor surface finish. The tool must be vented to avoid burn marks and prevent mold deposits.

**Note**

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